

AMENDMENTS

In The Claims:

1-162. (canceled)

163. (previously added) An electronic package comprising:

a substrate comprising silicon;

a die joined with said substrate; and

an upper metallization structure over said die, wherein said upper metallization structure comprises an electroplated metal.

164. (previously added) The electronic package in claim 163, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

165. (previously added) The electronic package in claim 163, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

166. (currently amended) The electronic package in claim 163, wherein an opening is in said substrate and accommodates said die, said substrate having a top surface coplanar with a top surface of said die, ~~and a bottom surface coplanar with a bottom surface of said die.~~

167. (previously added) The electronic package in claim 163 further comprising a polymer layer under a metal layer of said upper metallization structure.

168. (previously added) The electronic package in claim 163 further comprising a polymer layer over a metal layer of said upper metallization structure.

169. (previously added) The electronic package in claim 163, wherein said die has a top surface at a horizontal level, said substrate being under said horizontal level, said upper metallization structure being over said horizontal level.

170. (previously added) The electronic package in claim 169, wherein said top surface comprises multiple pads.

171. (previously added) The electronic package in claim 169 further comprising a passive device over said horizontal level.

172. (previously added) The electronic package in claim 163, wherein said upper metallization structure further extending outside beyond an edge of said die.

173. (previously added) The electronic package in claim 163 further comprising an adhesive tape joining said die and said substrate.

174. (previously added) The electronic package in claim 163 further comprising an a
conductive paste joining said die and said substrate

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